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### COMPUTING WITH NANO-CROSSBAR ARRAYS



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# **Project Details**

- Gathers globally leading research groups working on nanoelectronics and EDA
- Targets variety of emerging technologies including nanowire/nanotube crossbar arrays, magnetic switch-based structures, and crossbar memories
- Contributes to the construction of emerging computers beyond CMOS by proposing nano-crossbar based computer architectures.



Budget: 724500 EURO

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DEMOCRITUS UNIVERSITY OF THRACE

### **Project Details**



### **Project Details**



### Two-terminal vs. Four-terminal





### Two-terminal vs. Four-terminal

**Shannon's work**: A Symbolic Analysis of Relay and Switching Circuits(1938)



Parallel:  $x_1 + x_2$ 

Series:  $x_1$ .  $x_2$ 

2C:	Die Photos			6C: 1.17B Transistors 12MB L3				
384M Transistors 4MB L3	1	ΠÜ			introller Incore	U.U.	ii .	
Core1 Core0	Core0 V-Core	Core1 V-Core	Core2 V-Core	<b>Punggung</b>	Core3 V-Core	Core4 V-Core	Core5 V-Core	
		L3		LO F		L3		
Cache Westmere 2C		Cache V-Uncored Westmer			and the second			i ac

### Two-terminal vs. Four-terminal



(a)

(b)

What are the Boolean functions implemented in (a) ad (b)?

## Logic Synthesis











### **FET-based Model**



From Snider, G., et al., (2004). CMOS-like logic in defective, nanoscale crossbars. Nanotechnology.

### **FET-based Model**

**Example:** Implement the Boolean function f = A' with FET based nanoarrays using CMOS-like logic.



### **FET-based Model**

**Example:** Implement the Boolean function f = (A B + CD)' with **FET** based nanoarrays using **CMOS**-like logic.



### Four-terminal Switch-based Model



3 × 3 2D switching network and its lattice form

### Four-terminal Switch-based Model

- Switches are controlled by Boolean literals.
- $\Box$   $f_L$  evaluates to 1 iff there exists a top-to-bottom path.
- $\square$   $g_L$  evaluates to 1 iff there exists a left-to-right path.



### Logic Synthesis Problem

How can we implement a given target Boolean function  $f_T$  with a lattice of four-terminal switches?



### Logic Synthesis Problem



# Synthesis Method

**Example:**  $f_T = x_1 x_2 x_3 + x_1 x_4 + x_1 x_5$ 

- Start with  $f_T$  and its dual.
- Assign each product of  $f_T$  to a column.
- Assign each product of  $f_T{}^D$  to a row.
- Compute an intersection set for each site.
- Arbitrarily select a literal from an intersection set and assign it to the corresponding site.

$f_T^{\ D} = (x_1 + x_2 + x_3)(x_1 + x_4)(x_1 + x_5)$ $f_T^{\ D} = x_1 + x_2 x_4 x_5 + x_3 x_4 x_5$					
	$egin{array}{c} x_1 \ x_2 \ x_3 \end{array}$	$\begin{pmatrix} x_1 \\ x_4 \end{pmatrix}$	$x_1 \\ x_5$		
$x_1$	$x_1$	$x_1$	$x_1$		
$x_2 x_4 x_5$	<i>x</i> <sub>2</sub>	50	<i>x</i> <sub>5</sub>		
$x_3 x_4 x_5$	<i>x</i> <sub>3</sub>	<i>x</i> <sub>4</sub>	<i>x</i> <sub>5</sub>		

### **Experimental Results**

Implementation of fxore with different nanocrossbar types



### **Experimental Results**

Туре	Array Size Formulas
Diode	(number of products in $f$ ) x ("number of literals in $f$ "+
	1)
FET-	(number of literals in $f$ ) x ("number of products in $f$ "
CMOS	+ "number of products in $f^{\bar{D}}$ ")
Four-	(number of products in $f$ ) x (number of products in $f^{D}$ )
terminal	(number of products $\inf f$ ) x (number of products $\inf f$ )

Benchmark	FET-CMOS	Diode	4-Terminal	<b>Optimal 4-Terminal</b>
Del 2	72	36	16	12
Del 5	35	15	12	6
Del 6	36	18	9	6
Ex5 31	156	104	32	24
Ex5 33	110	77	21	21
Ex5 46	81	54	18	18
Ex5 49	72	54	12	12
Ex5 50	81	63	14	14
Ex5 61	64	48	12	12
Ex5 62	49	35	10	10
Misex1 1	48	16	8	8
Misex1 2	132	55	35	15
Misex1 3	156	60	40	24
Misex1 4	121	44	28	16
Misex1 5	90	45	25	15
Misex1 6	143	66	42	18
Misex1 7	81	36	20	15
Mp2d 4	345	75	90	24
Newtag	108	72	32	18

### **Defect/Fault Tolerance**



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**Permanent Faults** occur mostly in fabrication and are tolerated in post-fabrication by redundancy and reconfigurability (mapping). **Transient Faults** occur in field and are tolerated by redundancy

### **Defect/Fault Tolerance**

- Defect tolerance is achieved by realizing a target logic function on a defective crossbar using row and column permutations
- For the worst-case, N!M! permutations are required to find a successful mapping for NXM crossbar.
  - Defect-unaware algorithms aim to find the largest possible kXk defect-free sub-crossbar from a defective NXN crossbar where k ≤ N;
  - Defect-aware considers the defect characteristics (stuck-at-0 or stuck-at-1), then decide which switch to employ during the mapping.

### Technology Development for FET/Diode/Memristor based Arrays



**POST CMOS TECHNOLOGIES** 

### Technology Development for Four-Terminal Switch based Arrays

#### How about the technology?

- We propose CMOS-compatible technology with TCAD simulations
- By fitting the TCAD data to the standard CMOS current-voltage equations, we develop a Spice model of a four-terminal switch
- We are currently working toward the fabrication.

### **Device Structures**



- 1: Diffusion region 2: Gate electrode 3. Gate insulator region
- 4: Local Oxidation of Silicon (LOCOS) or Shallow Trench Isolation (STI) layers
- 5: Bulk layer

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# THANK YOU!